

## Product Change Notification - KSRA-22MRJA026

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**Date:**

10 Apr 2018

**Product Category:**

Temperature Sensors

**Affected CPNs:****Notification subject:**

CCB 3174 Final Notice: Qualification of CuPdAu bond wire in selected products of the 200K wafer technology available in 8L TDFN (2x3x0.8mm) package at NSEB assembly site

**Notification text:****PCN Status:**

Final notification

**PCN Type:**

Manufacturing Change

**Microchip Parts Affected:**

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products for 200K wafer technology available in 8L TDFN (2x3x0.8mm) package at NSEB assembly site

**Pre Change:**

Using gold (Au) bond wire, 8200T die attach, and G770HCD molding compound material

**Post Change:**

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach, and G700LTD molding compound material

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	UTAC Thai Limited LTD. (NSEB)	UTAC Thai Limited LTD. (NSEB)
<b>Wire material</b>	Au Wire	CuPdAu Wire
<b>Die attach material</b>	8200T	8600
<b>Molding compound material</b>	G770HCD	G700LTD
<b>Lead frame material</b>	C194	C194

**Impacts to Data Sheet:**

None

**Change Impact:**

None

**Reason for Change:**

To improve productivity by qualifying palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach, and G700LTD molding compound material at NSEB assembly site.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

May 10, 2018 (date code: 1819)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	November 2017					-- >	April 2018				May 2018				
	44	45	46	47	48		14	15	16	17	18	19	20	21	22
Workweek															
Initial PCN Issue Date					X										
Qual Report Availability								X							
Final PCN Issue								X							

Date																				
Estimated Implementation Date													X							

**Method to Identify Change:**

Traceability code

**Qualification Report:**

Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History:**

**November 29. 2017:** Issued initial notification.

**December 04. 2017:** Re-Issued initial PCN to correct the attachment.

**April 10. 2018:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date on May 10, 2018.

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_KSRA-22MRJA026\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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